MULTI-COM.PL





# Professional TFIX OP3 BGA Recovery Platform

Product ID: 21871

Price: **59.00 EUR**

Product weight: **1.00 kg**

## Description:

Professional TFIX OP3 BGA Recovery Platform is service platform for repairing smaller printed circuit boards such as cell phones and many other devices. Made of anodized aluminum with a steel base, it has two handles to securely secure the serviced PCB and a snap-in system with an additional spring provides the right pressure. The large, ground-insulated stand provides stability. Material from which it is made is resistant to overheating during service work, eg using hotair. This model also has a built-in positioners for iPhone systems for cleaning and preparation before reballing.

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Go to the product

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